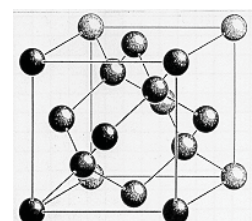
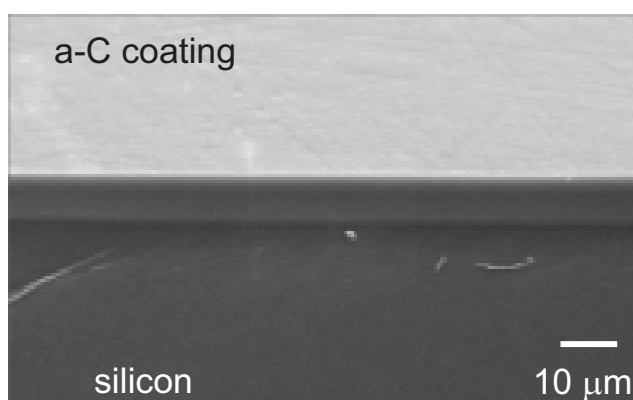
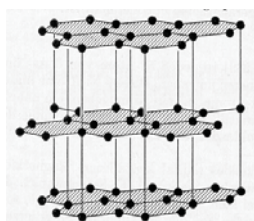


# Amorphe Kohlenstoffschichten und deren Eignung als biofunktionale Oberflächen

Michael Stüber

INSTITUTE FOR APPLIED MATERIALS – APPLIED MATERIALS PHYSICS (IAM-AWP), DEPARTMENT OF COMPOSITES AND THIN FILMS



KIT – University of the State of Baden-Wuerttemberg and  
National Research Center of the Helmholtz Association

[www.kit.edu](http://www.kit.edu)

## Outline

- relevance of amorphous and diamondlike carbon coatings
- DLC coatings – some fundamental aspects
- DLC coatings – from R&D level to industrial production
- DLC coatings – future challenges

## Applications in medicine and pharmacy ...



knee-prosthesis  
(IonBond AG)



urology: catheter  
(OptiMed Medizinische  
Instrumente GmbH)



one way syringe  
(Sulzer Metaplas)



chirurgical instruments  
(Plascotec GmbH)

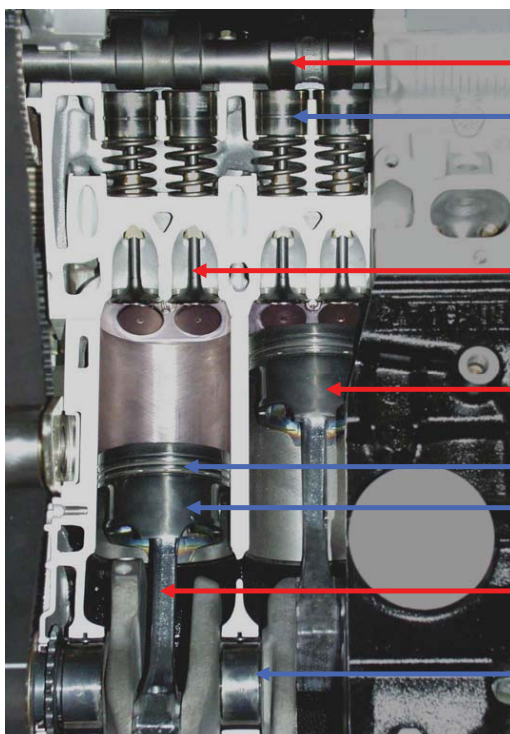


cardiovascular valve  
(St.Jude Medical)



tableting tool  
(Notter GmbH)

## ... applications in engineering



camshaft

tappets

valves

piston

piston ring

piston pin

drive rod

crankshaft  
bearing



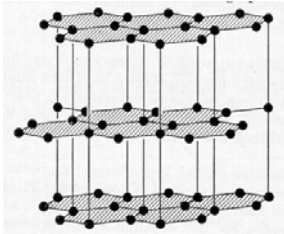
Fraunhofer IST, Braunschweig



Rübig GmbH

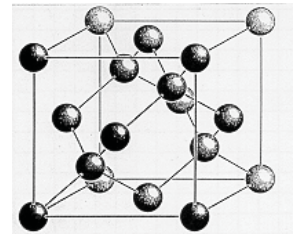
G. van der Kolk, IonBond AG, PSE 2006

graphite



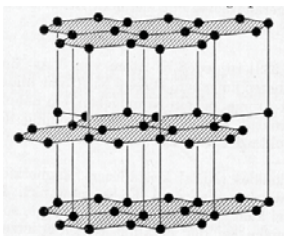
$sp^2$  bonds

diamond



$sp^3$  bonds

graphite



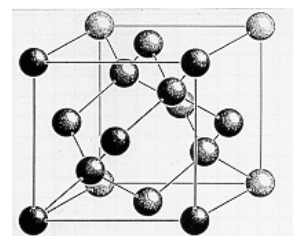
$sp^2$  bonds

a-C, a-C:H

ta-C, ta-C:H

carbon-based coatings

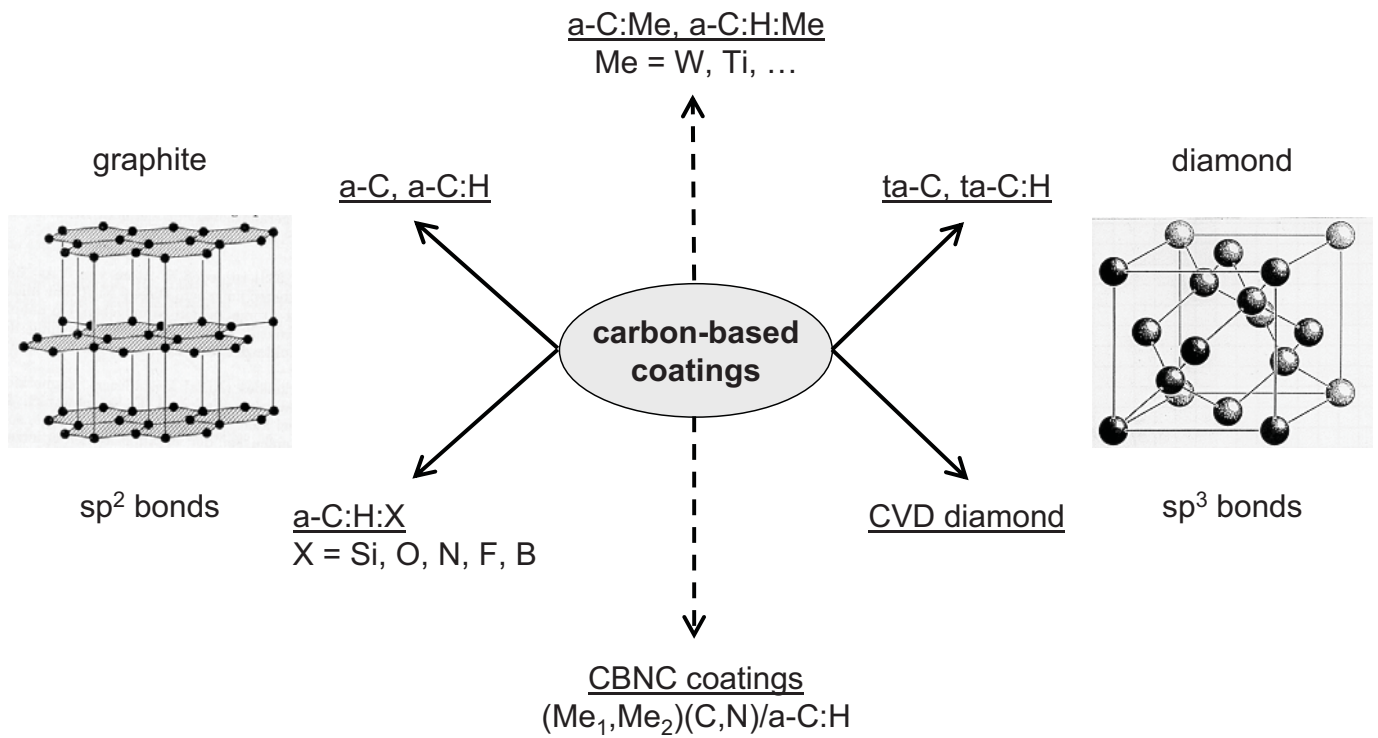
diamond



$sp^3$  bonds

a-C:H:X  
X = Si, O, N, F, B

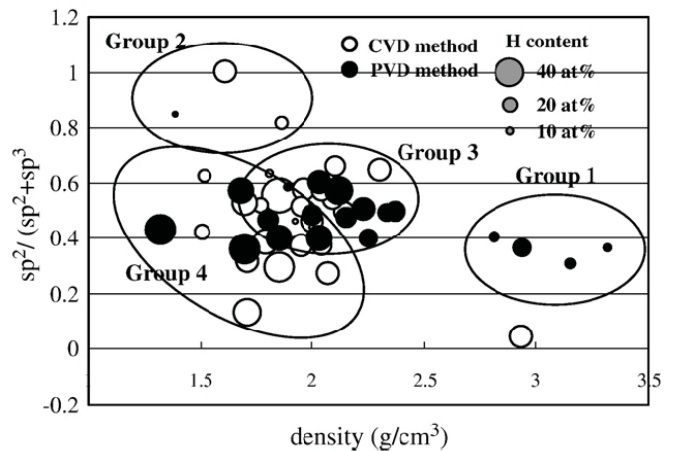
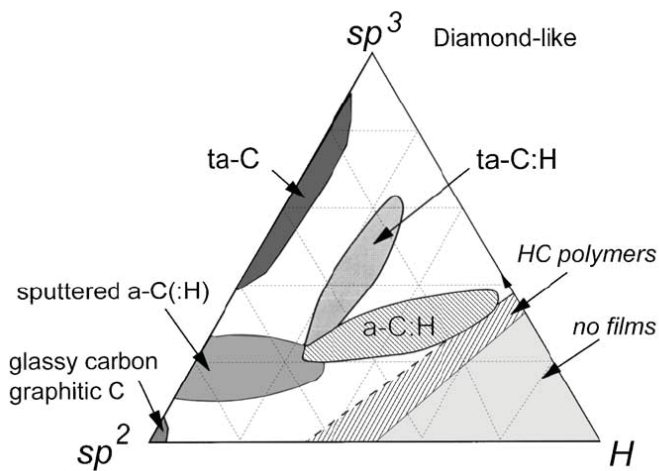
CVD diamond



Classification of amorphous carbon coatings

Ternary phase diagram of bonding states in amorphous carbon and carbon-hydrogen materials

Variations of the  $sp^2/(sp^2+sp^3)$  ratio versus the density of DLC films

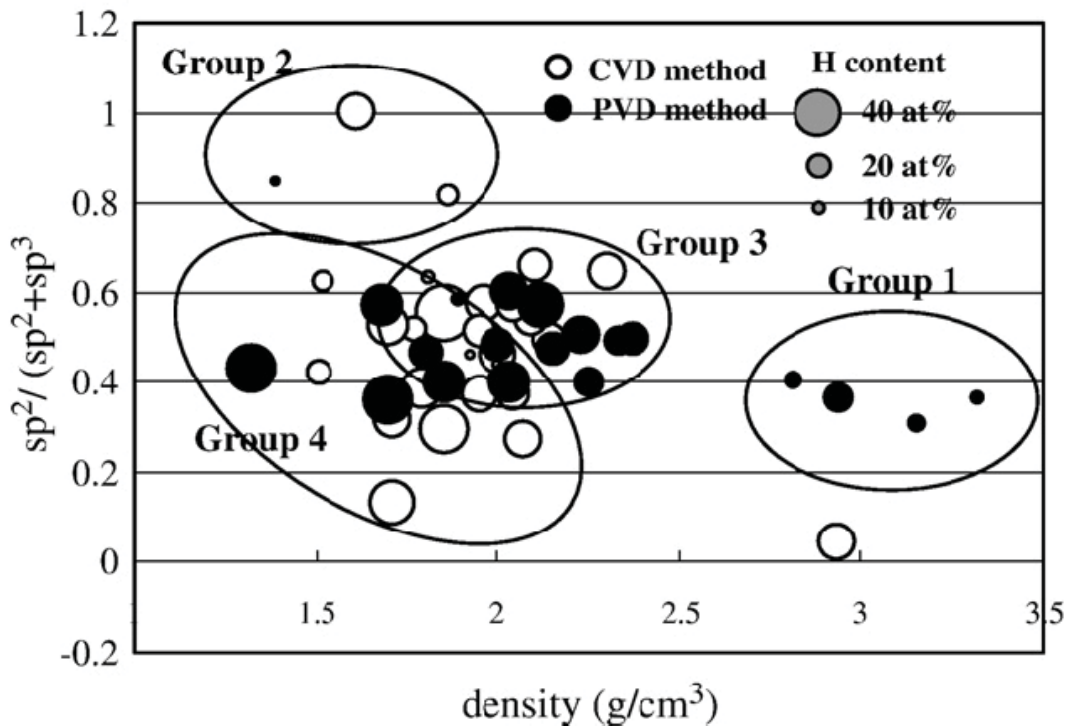
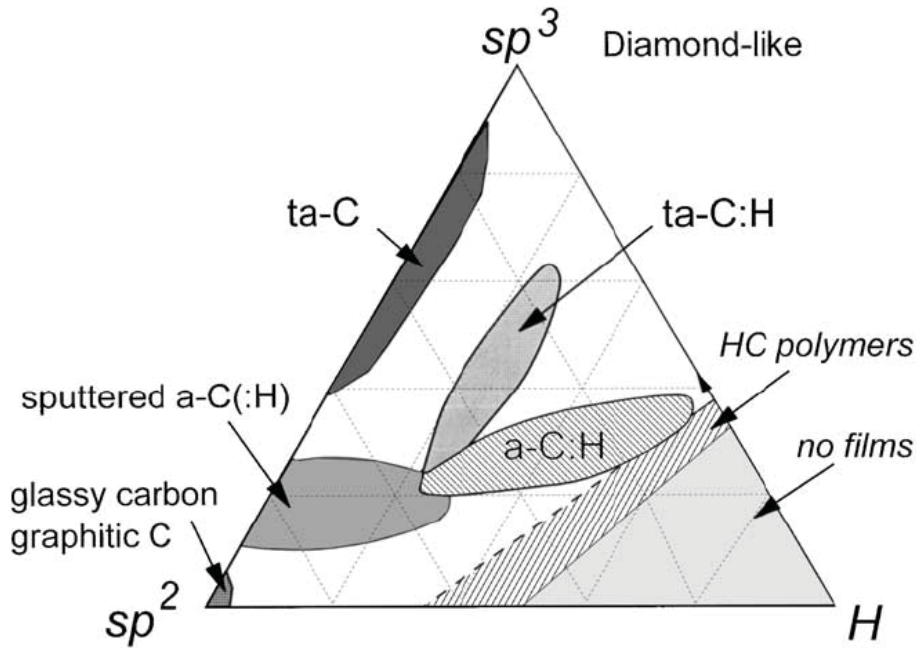


J.Robertson, Mat. Sci. Eng. R 37 (2002) 129

A.Saikubo et al., Diam. Rel. Mat. 17 (2008) 1743

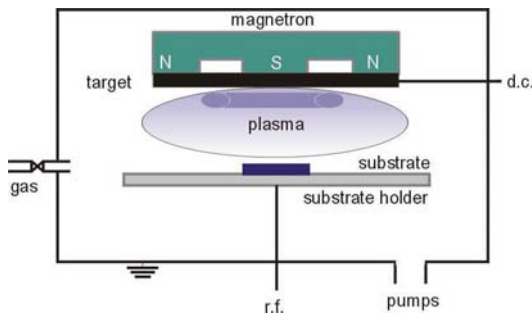
A.C.Ferrari, J.Robertson, Phys. Rev. B 61 (2000) 14095

W.Jacob, W.Möller, Appl. Phys. Lett. 63 (1993) 1771



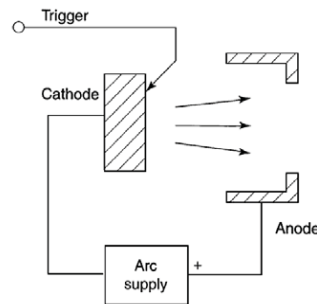


## magnetron sputtering



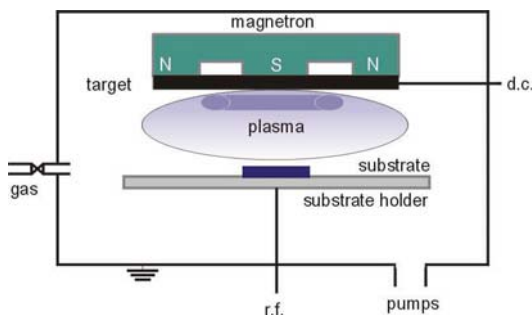
- non-equilibrium process
- low temperature
- no ions
- low deposition rate
- low particle energies

## cathodic arc evaporation



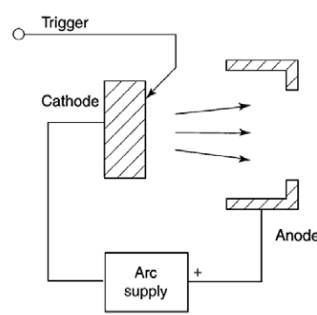
- non-equilibrium process
- low temperature
- 100% ions
- high deposition rate
- high particle energies

## magnetron sputtering



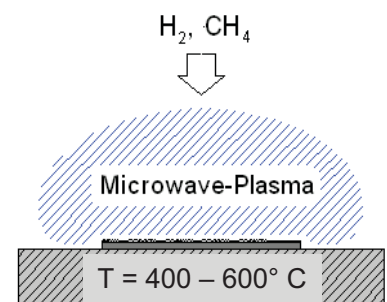
- non-equilibrium process
- low temperature
- no ions
- low deposition rate
- low particle energies

## cathodic arc evaporation



- non-equilibrium process
- low temperature
- 100% ions
- high deposition rate
- high particle energies

## plasma assisted CVD



- equilibrium process
- higher temperature
- molecules, radicals
- high deposition rate
- various particle energies

## DLC synthesis – materials science point of view



DLC = amorphous carbon material with a significant fraction of  $sp^3$  bonds

A.C.Ferrari, J.Robertson, Phys. Rev. B 61 (2000) 14095

## DLC synthesis – materials science point of view



DLC = amorphous carbon material with a significant fraction of  $sp^3$  bonds

A.C.Ferrari, J.Robertson, Phys. Rev. B 61 (2000) 14095

gas pressure, gas flow  
cathode power densities  
substrate temperature  
substrate bias

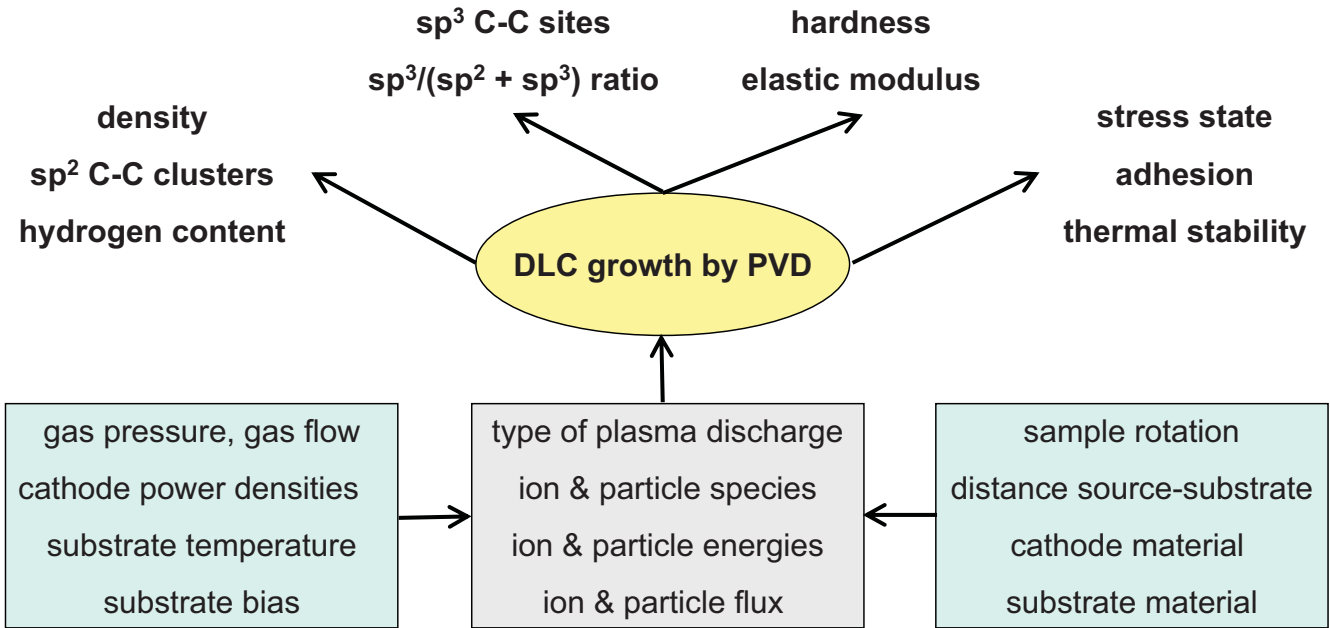
sample rotation  
distance source-substrate  
cathode material  
substrate material

**plasma deposition control for DLC growth by PVD**

# DLC synthesis – materials science point of view

DLC = amorphous carbon material with a significant fraction of  $sp^3$  bonds

A.C.Ferrari, J.Robertson, Phys. Rev. B 61 (2000) 14095



plasma deposition control for DLC growth by PVD

# Scale-up of magnetron sputtering processes

## laboratory scale

Leybold Z 550  
targets < 150 mm



## production scale

Hauzer HTC 625/Metaplas MZR 304/RF  
targets: ca. 400 mm x 125 mm





**demands on  
DLC technology**

## Functionality & Performance

hardness – toughness  
thermal & chemical stability  
wear resistance  
friction properties  
multi-purpose coatings

**demands on  
DLC technology**

## Coating design

ultrathin – thick coatings  
adhesion – stress management  
interface engineering  
Smooth, dense structures  
amorphous – columnar growth

**Functionality & Performance**

- hardness – toughness
- thermal & chemical stability
- wear resistance
- friction properties
- multi-purpose coatings

**Production technology**

- process stability & reliability
- processing costs
- high volume deposition
- high DLC growth rates
- coating quality

**demands on  
DLC technology**

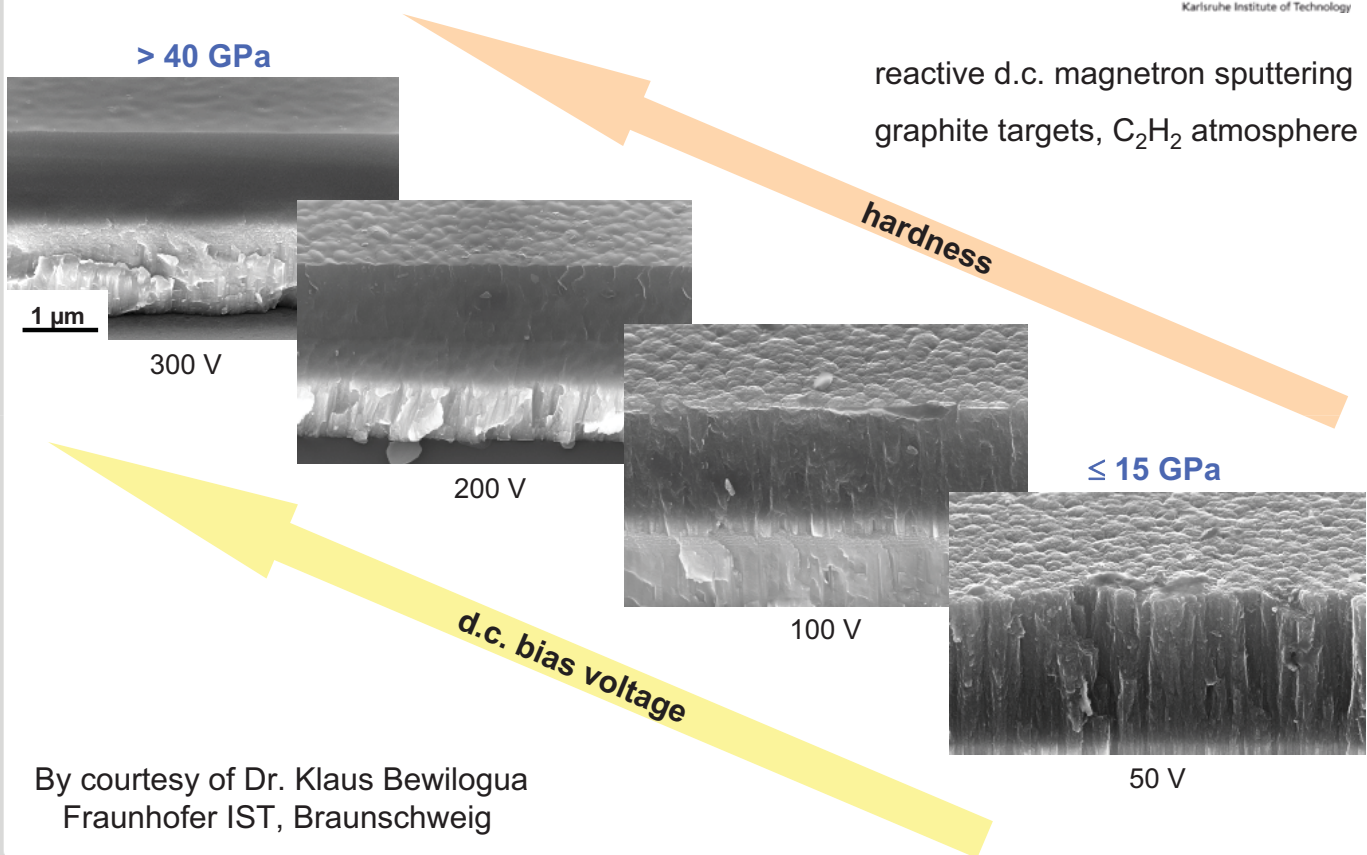
**Coating design**

- ultrathin – thick coatings
- adhesion – stress management
- interface engineering
- Smooth, dense structures
- amorphous – columnar growth

**Technology development**

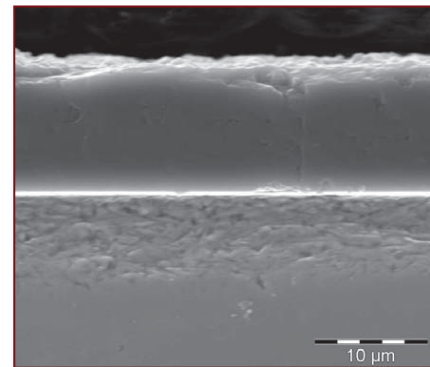
- high density plasma processes
- low temperature deposition
- multi-capability coating systems
- hybrid technologies
- pulsed methods (HIPIMS)

## Structure and properties of C-DLC coatings



## physical / chemical properties

composition	nearly 100% carbon, < 1 at.-% H
density	2.4 – 3.2 g/cm <sup>3</sup>
electr. resistivity	10 <sup>3</sup> – 10 <sup>6</sup> Wcm
refraction index	2.5 (at 700 nm wave length)
chem. resistance	inert (not against oxidising media and iron metals at elevated temp.)



amorphous ta-C structure  
sp<sup>3</sup> (C-C) dominated

## mechanical / tribological properties

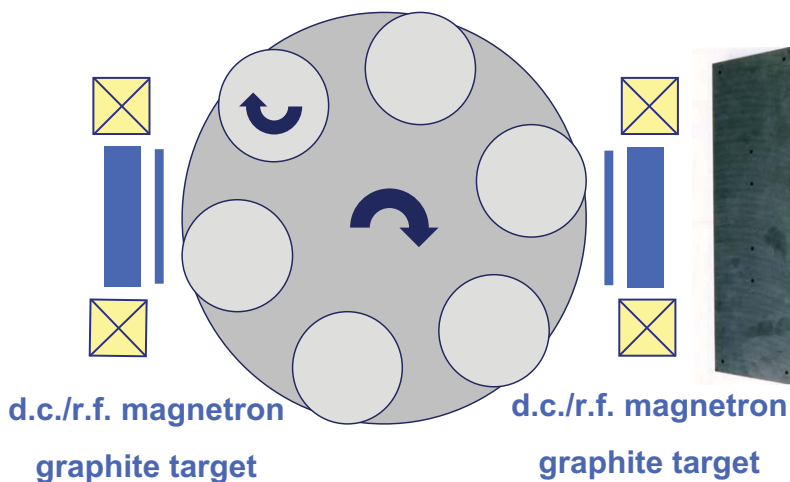
Young´s modulus	400 – 650 GPa
hardness	40 – 65 GPa
coefficient of friction	0.10 – 0.15 (against steel under dry sliding conditions)

**Laser-Arco®** and **Diamor®** are copyrights of the **Fraunhofer Gesellschaft e.V**

By courtesy of Dr. HaJo Scheibe  
Fraunhofer IWS, Dresden

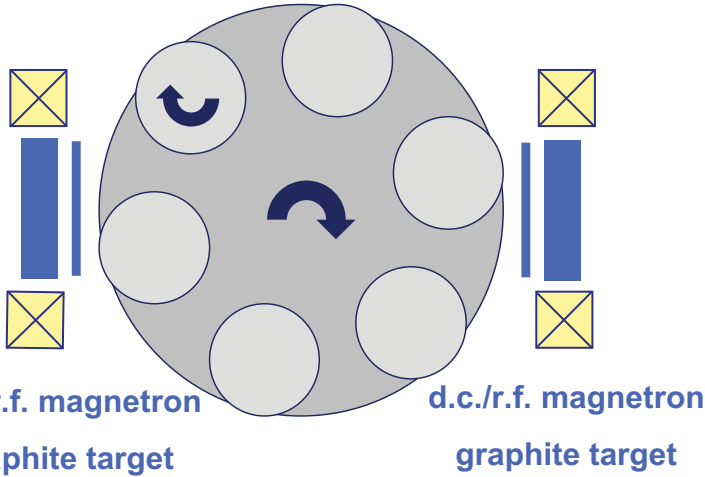
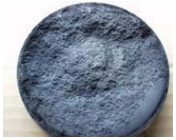
# Hard a-C and ta-C films by novel hybrid PVD processes

Metaplas MZR 304/RF system at IAM  
**modular PVD/PA-CVD system**  
reactive d.c./r.f. magnetron sputtering



advanced d.c. arc module

graphite cathode



d.c./r.f. magnetron  
graphite target

d.c./r.f. magnetron  
graphite target

Metaplas MZR 304/RF system at IAM

modular PVD/PA-CVD system

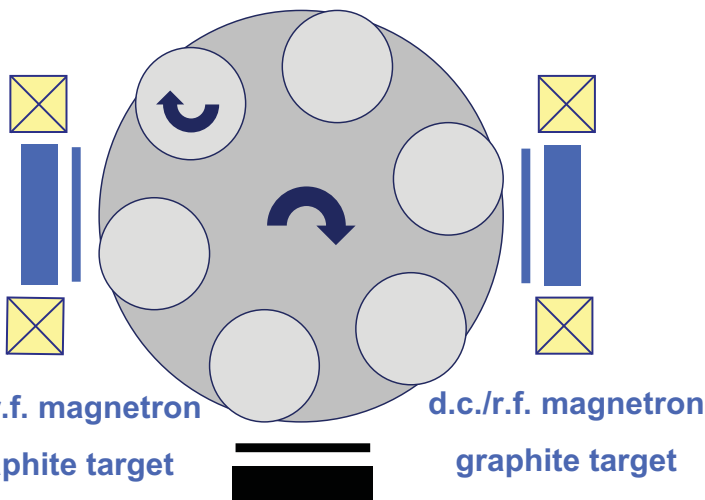
reactive d.c./r.f. magnetron sputtering

d.c. cathodic arc evaporation

magnetic field configuration tuning

advanced d.c. arc module

graphite cathode



d.c./r.f. magnetron  
graphite target

d.c./r.f. magnetron  
graphite target

flexible flange position  
(i.e. pulsed magnetron)

Metaplas MZR 304/RF system at IAM

modular PVD/PA-CVD system

reactive d.c./r.f. magnetron sputtering

d.c. cathodic arc evaporation

magnetic field configuration tuning

d.c./r.f. substrate bias

low temperature deposition up to 500°C



large variation in modification of

**plasma density**

**plasma particle energies**

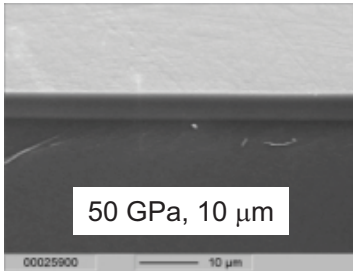
**substrate current density**

**growth conditions for hard a-C films**

# Structure and properties of a-C and ta-C coatings

## magnetron sputtering

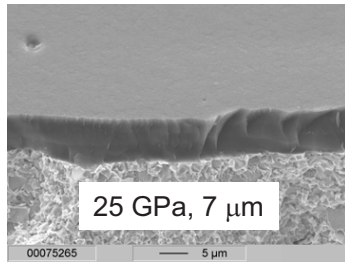
temperature < 100°C, d.c./r.f. bias gradient



lab-scale process  
stationary  
target: 11 W/cm<sup>2</sup>

development

upscaled process  
3-fold rotation  
target: 4 W/cm<sup>2</sup>

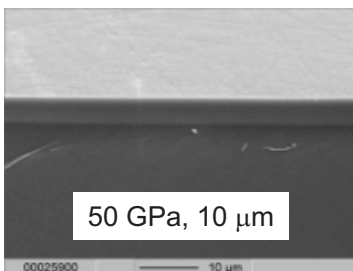


$$\begin{matrix} < 0,1 & A_{\text{target}}/A_{\text{table}} & \sim 1 \\ < 10 \text{ cm} & D_{\text{target-table}} & \gg 10 \text{ cm} \end{matrix}$$

# Structure and properties of a-C and ta-C coatings

## magnetron sputtering

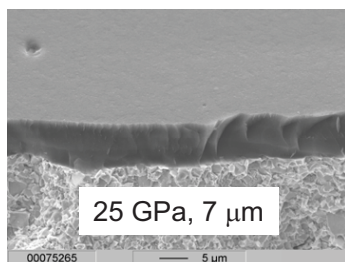
temperature < 100°C, d.c./r.f. bias gradient



lab-scale process  
stationary  
target: 11 W/cm<sup>2</sup>

development

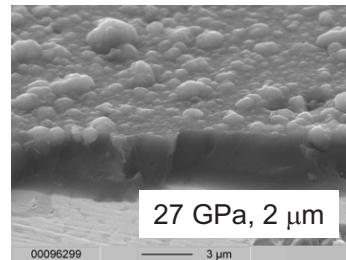
upscaled process  
3-fold rotation  
target: 4 W/cm<sup>2</sup>



$$\begin{matrix} < 0,1 & A_{\text{target}}/A_{\text{table}} & \sim 1 \\ < 10 \text{ cm} & D_{\text{target-table}} & \gg 10 \text{ cm} \end{matrix}$$

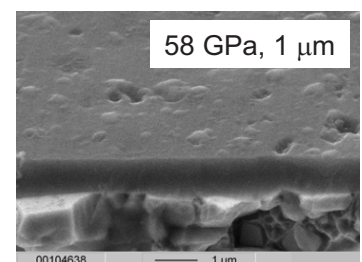
## cathodic arc evaporation

temperature < 100°C, d.c. bias gradient



high current arc  
start pressure: high  
end pressure: low

lower current arc  
low pressure



ta-C dependent on thermal process management ?



more than 100 data sets on industrially available DLC (and other carbon-based) coatings of various companies, job-coaters and end-users can be found at

[www.ist.fraunhofer.de](http://www.ist.fraunhofer.de)

(focus mainly on Germany, Switzerland, Austria, The Netherlands)

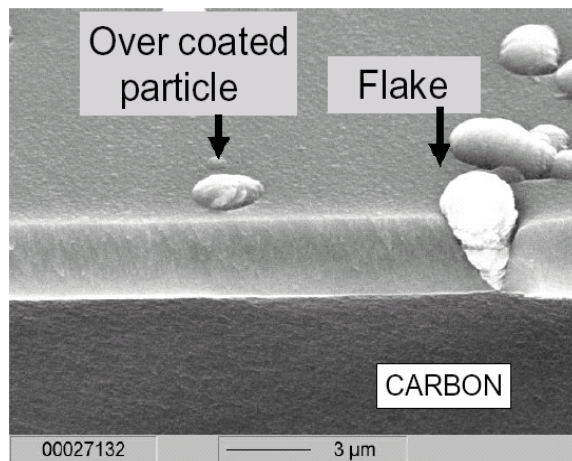
→ strong need for harmonization

↓  
**Technical Guideline VDI 2840**  
of the Society of German Engineers

ICS 25.220.99 VDI-RICHTLINIEN November 2005

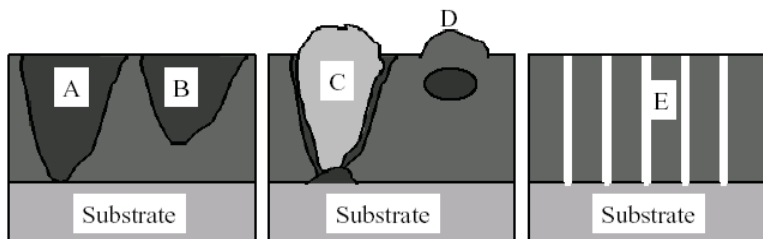
VEREIN DEUTSCHER INGENIEURE	Kohlenstoffschichten Grundlagen, Schichttypen und Eigenschaften Carbon films Basic knowledge, film types and properties	VDI 2840 Ausg. deutsch/englisch Issue German/English
Die deutsche Version dieser Richtlinie ist verbindlich. The German version of this guideline shall be taken as authoritative. No guarantee can be given with respect to the English translation.		
<b>Inhalt</b>	<b>Seite</b>	<b>Contents</b>
1 Einleitung und Zielsetzung	2	1 Introduction and objectives
2 Geltungsbereich	3	2 Scope of application
3 Grundlagen	5	3 Fundamental principles
3.1 Kristallgitter des Kohlenstoffs	5	3.1 Crystal lattice of carbon
3.2 Bindungstypen	6	3.2 Bond types
3.3 Atomnetzwerke der amorphen Kohlenstoffschichten	7	3.3 Atomic networks of the amorphous carbon films
3.4 Beschichtungsverfahren	8	3.4 Coating methods
4 Schichttypen	11	4 Film types
5 Schichtigenschaften	24	5 Coating properties
5.1 Hinweise für die Bestimmung der Schichtigenschaften	24	5.1 Instructions on determining coating properties
5.1.1 Adhäsiv-Verschleißschutz	25	5.1.1 Protection against adhesive wear
5.1.2 Abrasiv-Verschleißschutz	26	5.1.2 Abrasive wear protection
5.1.3 Schutz gegen Oberflächenzerstörung	26	5.1.3 Protection against surface fatigue
5.1.4 Schutz gegen chemischen Verschleiß	27	5.1.4 Protection against chemical wear
5.1.5 Reibungsreduzierung	28	5.1.5 Reduction in friction
5.1.6 Benetzbarkeit	28	5.1.6 Wettability
5.1.7 Sonderfunktionen	28	5.1.7 Special functions
5.1.8 Schichtdicke	29	5.1.8 Film thickness
5.1.9 Schichtrauheit	30	5.1.9 Film roughness
5.1.10 Farbdruck und Helligkeit	31	5.1.10 Colour sensation and lightness
5.1.11 Menge Dotierung/Zusatzstoffe	32	5.1.11 Quantity of doping or additives
5.1.12 Temperaturbeständigkeit	32	5.1.12 Heat resistance
5.1.13 Wärmeleitfähigkeit	33	5.1.13 Thermal conductivity
5.1.14 Wärmeausdehnung	33	5.1.14 Thermal expansion
5.1.15 Härte und Elastizitätsmodul	33	5.1.15 Hardness and modulus of elasticity
5.1.16 Spezifischer elektrischer Widerstand	34	5.1.16 Specific electrical resistance (electrical resistivity)
5.2 Beschichtbare Substratmaterialien	34	5.2 Coatable substrate materials
Schrifttum	37	Bibliography
Bildnachweis	39	Illustration credits
Glossar	40	Glossary
VDI-Gesellschaft Produktionstechnik (ADB) Arbeitskreis CVD-Diamant-Verzuga VDI-Handbuch Betriebstechnik, Teil 3 VDI-Handbuch Werkstofftechnik		

## DLC: Challenges – growth defects in PVD coatings



growth defects in magnetron sputtered carbon coatings:

J.Vetter, M.Stüber, S.Ulrich  
 Surf. Coat. Tech. 168 (2003) 169



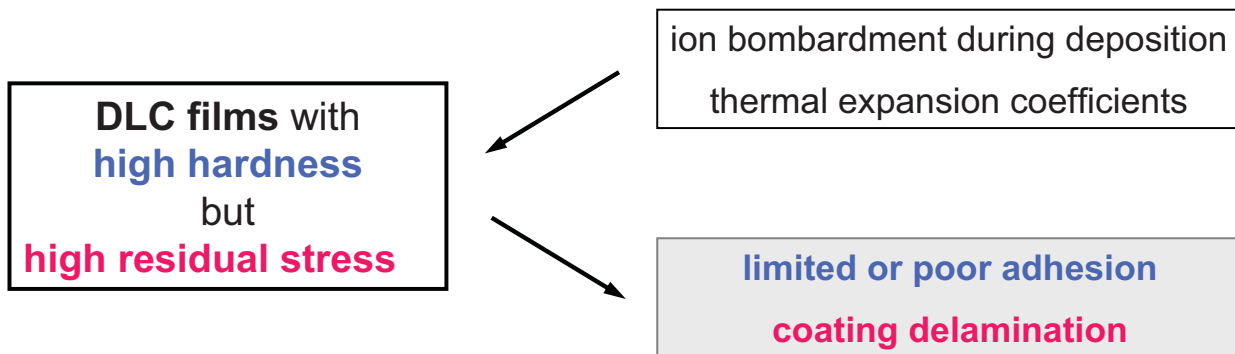
Voids  
 A) till substrate  
 B) in the coating

Particles in the coating  
 C) flake formation  
 D) over coated particle

Morphology:  
 E) coarse columnar

## DLC: Challenges – intrinsic stress and adhesion

objective: DLC deposition on metal substrates (i.e. AISI 316 L)



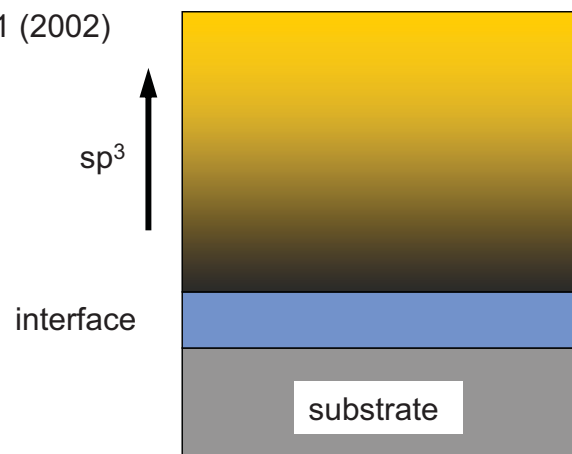
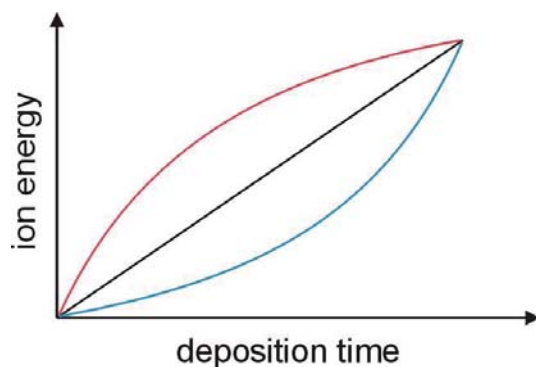
**coating design for reducing the residual stress:**

- additions of e.g. metal or N: a-C:X coatings
- multilayer concepts
- advanced gradient coating concepts

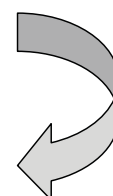


## Advanced gradient coating concept for stress management

FZK-patents: US 6.110.129 (2000), EP 0912774 B1 (2002)



**gradient superhard ta-C coatings on steel:**  
Vickers hardness 50 GPa, thickness 10  $\mu\text{m}$ ,  
critical load of failure > 30 N, < 1 GPa stress



DLC coatings for artificial hip joints

- **in vitro** excellent performance of DLC

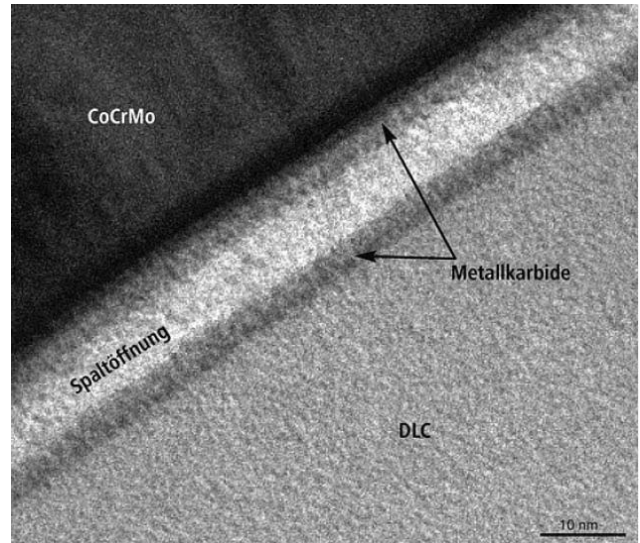
DLC as wear resistant, chemically inert and biocompatible functional coating

but !

- **in vivo: failure of implant**

due to failure of interface layer between implant and functional DLC coating by

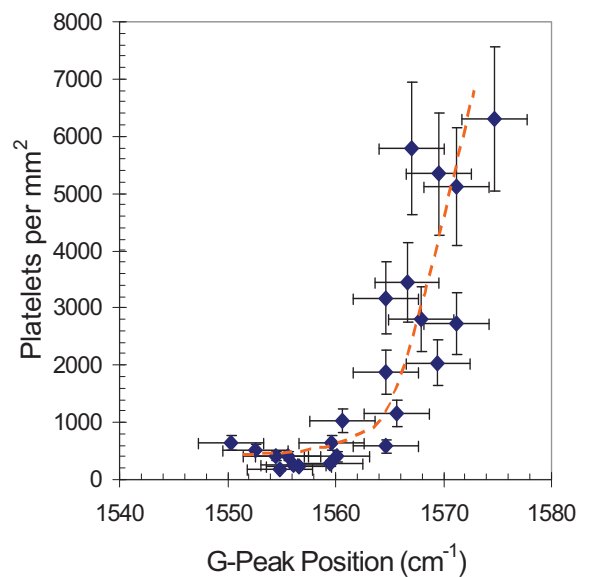
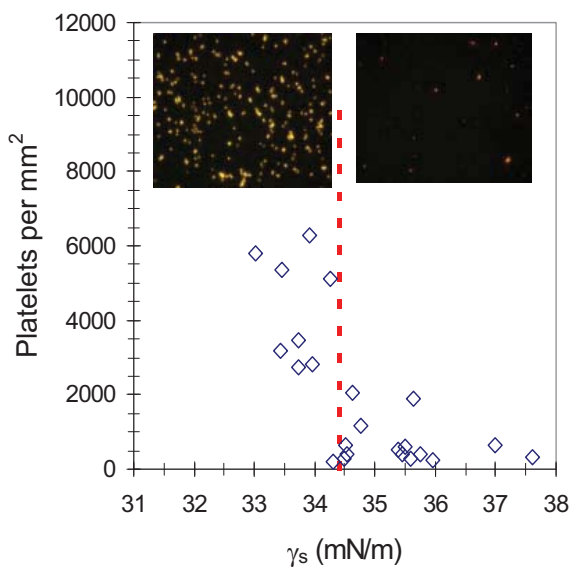
- crack formation at interface
- crack propagation through interface
- delamination of DLC coating
- corrosion of implant material



DGM News 2010  
 C.V.Falub et al., Acta Biomater. 5 (2009) 3086  
 U.Müller et al., Acta Materialia 59 (2011) 1150  
 R.Hauert et al., Diam. Rel. Mat. 25 (2012) 34  
 R.Hauert et al., Acta Biomater. 8 (2012) 3170

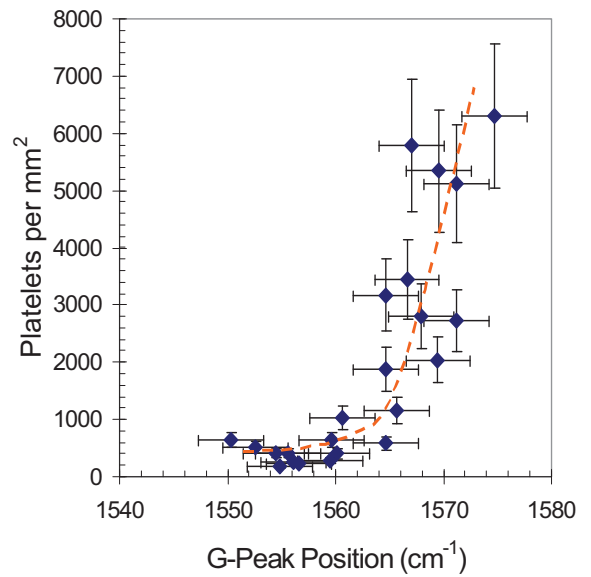
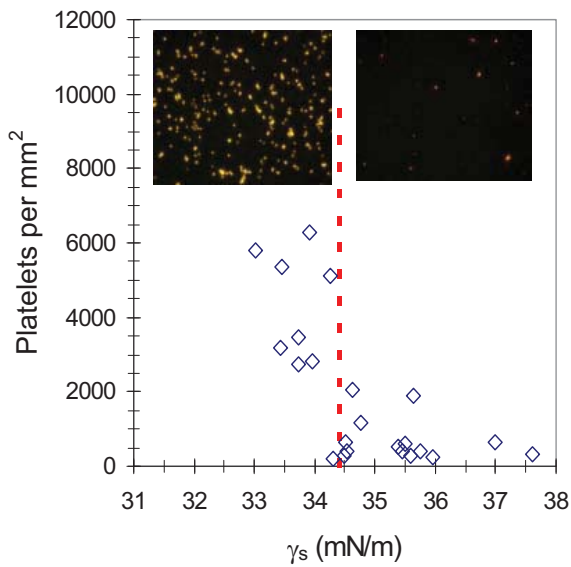
DLC: challenges – surfaces with predictable cell adhesion ?

adhesion of thrombocytes on magnetron-sputtered a-C:X coatings



thrombocyte adhesion = f (surface energy, a-C:X constitution, morphology)

adhesion of thrombocytes on magnetron-sputtered a-C:X coatings



thrombocyte adhesion = f (surface energy, a-C:X constitution, morphology)

But: protein adsorption (Albumin, Fibrinogen, ...) before cell adhesion ! ?

modelling & simulation of DLC growth  
optimized DLC deposition processes



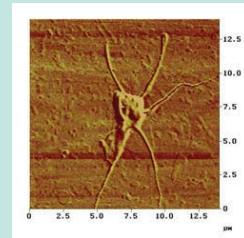
pulsed processes (HIPIMS)  
hybrid processes  
high rate deposition

**modelling & simulation of DLC growth**  
**optimized DLC deposition processes**

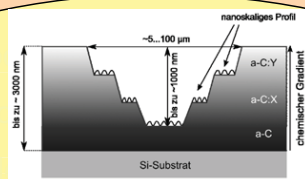
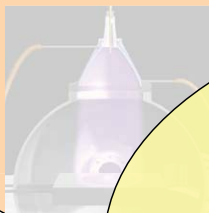


pulsed processes (HIPIMS)  
 hybrid processes  
 high rate deposition

unspecific interactions  
 specific interactions  
 cell – surface interactions  
 materials science – physics – chemistry - biology  
**protein interaction at DLC surfaces**



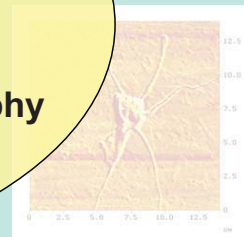
**modelling & simulation of DLC growth**  
**optimized DLC deposition processes**



plasma chemical modification a-C:O:X  
 surface functionalization

**DLC advanced surface topography**  
 nanoscale surface re-arrangement  
 surface micropatterning

**protein interaction at DLC surfaces**





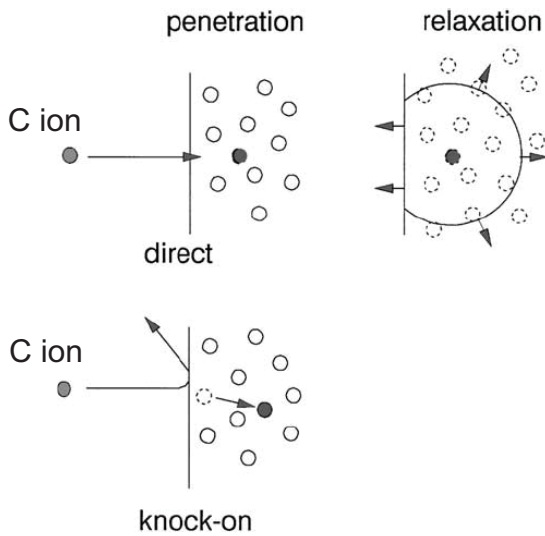
Many thanks to  
S.Ulrich, H.J.Seifert,  
L.Niederberger, F.Danneil,  
all colleagues of Department Composites and Thin Films (IAM-AWP),  
A.Welle and team at IBG-1

All colleagues quoted in the presentation

**Thank you for your kind attention !**

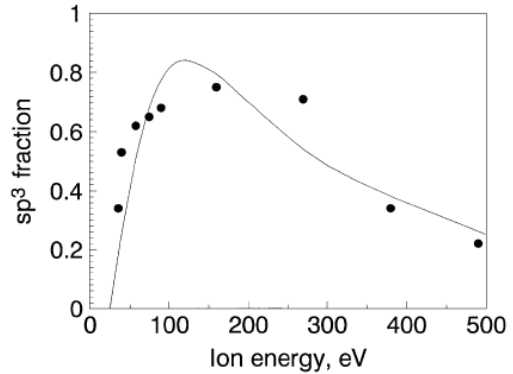
RESERVE

example: amorphous carbon, a-C



## subplantation model

metastable increase in local density  
local conversion of  $sp^2$  to  $sp^3$  sites



compressive stress & thermal spike models ?

J.Robertson, Pure & Appl. Chem. 66 (1994) 1789

J.Robertson, Mat. Sci. Eng. R 37 (2002) 129

Y.Lifshitz et al., Phys. Rev. B 41 (1990) 10468

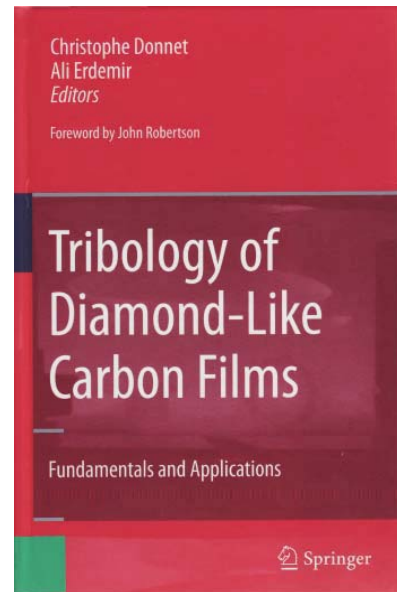
S.Neuville, A.Matthews, Thin Solid Films 515 (2007) 6619

# DLC films – R&D milestones and state-of-the-art

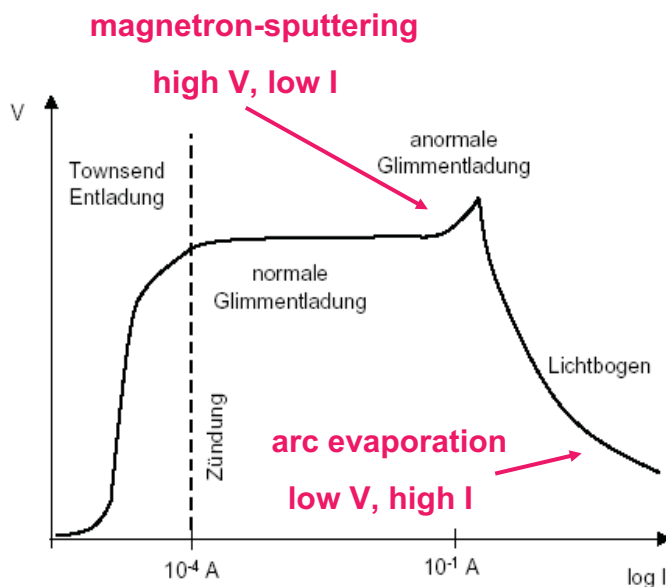
1953	H.Schmellenmeier DC glow discharge of $C_2H_2$
1971	S.Aisenberg, R.Chabot ion beam deposition from graphite
1976/77	L.Holland, S.M.Ohja RF glow discharge of $C_4H_{10}$
1979/80	C.Weissmantel et al. / K.Enke et al. friction and tribology of DLC
1981	F.K.King carbon films for magnetic recording media
1983	H.Dimigen et al. a-C:H:Me coating film family, Me = W, Ti, ...
1986	J.Robertson, Adv. Phys. 35 (1986) 317
1990	D.R.McKenzie et al., H.J.Scheibe et al. arc techniques (filtered arc, laser arc)
1994	M.Grischke et al., and other groups a-C:H:X coating family, X = F, Si, O, B, N
1997/98	A.Voevodin J.Zabinski et al.
> 2000	multilayers, gradient coatings, nano-composites, „chameleon coatings“

## DLC films – R&D milestones and state-of-the-art

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## Fundamental aspects of cathodic arc evaporation



voltage – current characteristics  
of glow discharges

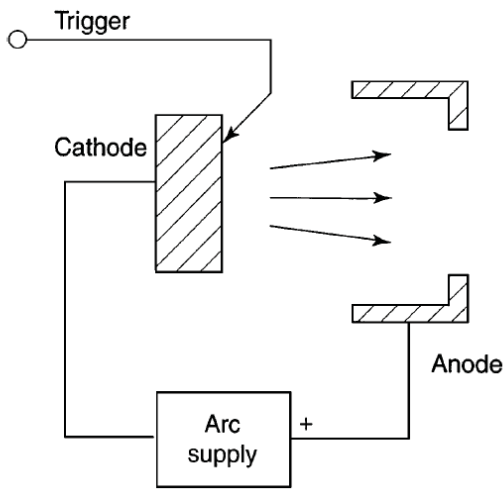
arc discharge: **collective electron emission**  
glow discharge: individual electron emission

**kinetic energy of particles 20 – 150 eV**  
(magnetron sputtering 5 – 10 eV)

**highly or fully ionized arc plasma**  
multiply charged ions  
(carbon arc plasma: 60 - 100%  $C^+$ )

**droplet & macroparticle emission**

**cathode spot dynamics** = f (cohesive energy of  
cathode material & magnetic field configuration)



simplified schematic of basic cathodic arc configuration

## characteristics of cathodic vacuum arc

low-voltage, high-current plasma discharge

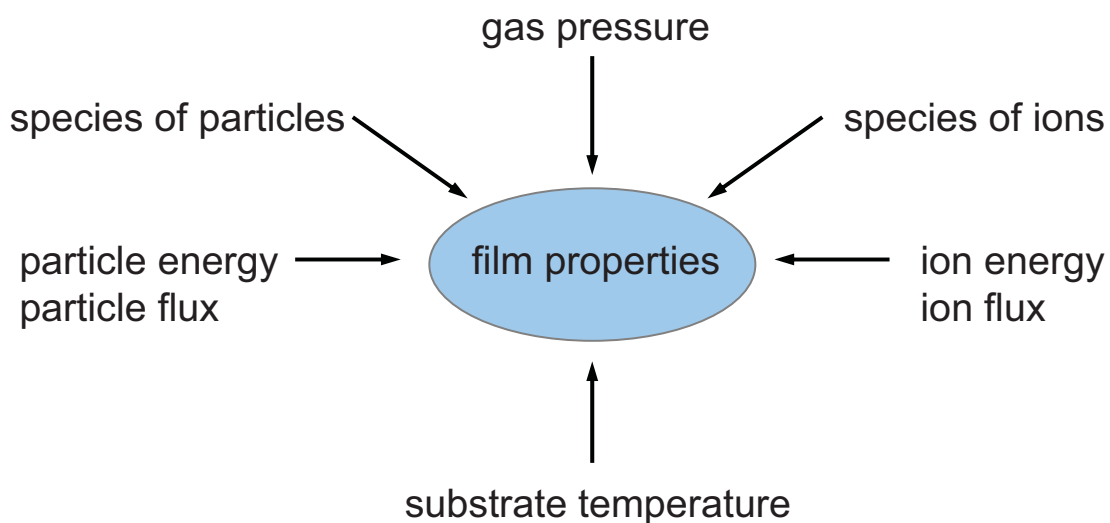
formation of discrete „cathode spots“

explosive emission process (including particles)

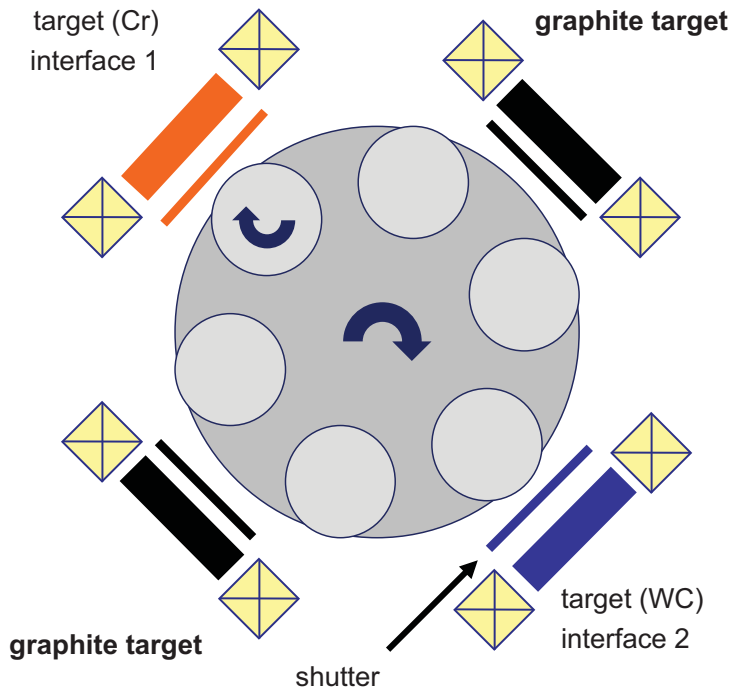
cathode spot size:	1 – 10 $\mu\text{m}$
current density at cathode spot:	$10^6 - 10^8 \text{ A/cm}^2$
power density at cathode spot:	$10^7 - 10^9 \text{ W/cm}^2$
electric field at cathode spot:	$10^4 - 10^5 \text{ V/cm}$
temperature at cathode spot:	4000 – 40000 K
pressure at cathode spot:	0.1 – 10 MPa
lifetime of a spot at a fixed location:	10 ns – 1 $\mu\text{s}$
high ion density:	$10^{13}/\text{cm}^2$
multiple charge states:	$\text{Me}^+, \text{Me}^{2+}, \text{Me}^{3+}$
kinetic energy of ions:	10 – 200 eV

I.G.Brown, Annu. Rev. Mater. Sci. 28 (1998) 243

# Control of deposition processes



# DLC films by reactive d.c. magnetron sputtering (C-DLC)



## process parameters & characteristics

reactive d.c. magnetron sputtering  
 graphite targets, UBM mode  
 target power density up to 8 W/cm<sup>2</sup>  
 total gas pressure 0.2 – 0.4 Pa

- variation of C<sub>2</sub>H<sub>2</sub> gas flow
- variation of d.c. substrate bias
- variation of coil current
- d.c. pulse (targets, substrate)



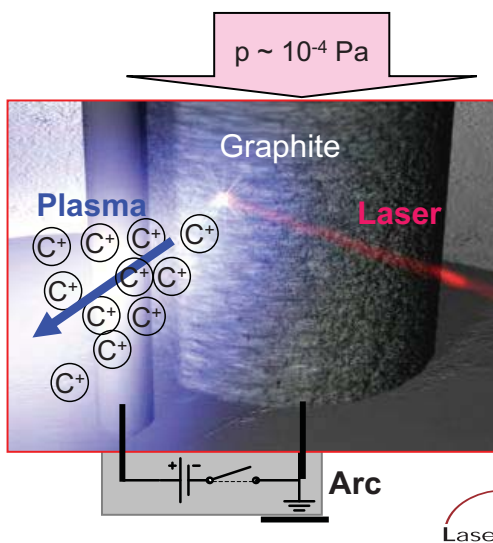
**enhanced plasma density**  
**increased substrate current density**

K.Bewilogua et al, presentation at ICMCTF 2008, San Diego

coating type 2.4 (a-C:H), VDI 2840

# DLC by laser controlled pulsed arc evaporation (Laser-Arc)

**superhard, hydrogen free ta-C films**



## process parameters & characteristics

pulsed laser arc plasma source  
 rotating graphite cathode  
 high vacuum process (10<sup>-4</sup> Pa)

- variation of pulsed arc current
- variation of arc puls duration
- variation of deposition temperature
- variation of carbon incident angle on the substrate



**highly ionized carbon plasma**  
**high carbon ion energies (> 30 eV)**  
**low substrate temperature (T < 100°C)**

system industrially available → exhibition

P.Siemroth, H.J.Scheibe, IEEE Trans. Plas. Sci. 18 (1990) 911

coating type 2.2 (ta-C), VDI 2840



Tabelle 1. Einteilung der Kohlenstoffschichten, siehe auch Erläuterungen im Textteil

Bezeichnung (englischer Name)	Kohlenstoffschichten															
	1 Plasma-polymer-schichten (plasma-polymer films)	2 Amorphe Kohlenstoffschichten (amorphous carbon films, diamond-like-carbon films/DLC)							3 Kristalline Kohlenstoff-Schichten (crystalline carbon films)							
Dünnschicht/Dickschicht	Dünnschicht	Dünnschicht														
Dotierung, Zusatzstoffe		wasserstofffrei			wasserstoffhaltig				undotiert		dotiert		undotiert		dotiert	
Kristallgröße auf der Wachstumsseite		(amorph)														
Überwiegende C-C-Bindungsart	sp <sup>2</sup> oder sp <sup>3</sup> , lineare Bindung	sp <sup>2</sup>	sp <sup>3</sup>	sp <sup>2</sup>	sp <sup>2</sup> oder sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>2</sup>	sp <sup>2</sup>	sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>2</sup>	
Schicht-Nr.	1	2.1	2.2	2.3	2.4	2.5	2.6	2.7	3.1	3.2	3.3	3.4	3.5	3.6		
Bezeichnung	Plasmapolymer-schicht	Wasserstoff-freie amorphe Kohlenstoffschicht	Tetraedri-sche wasserstofffreie amorphe Kohlenstoff-schicht	Metallhal-tige wasserstofffreie amorphe Kohlenstoff-schicht	Wasserstoff-haltige amorphe Kohlenstoff-schicht	Tetraedri-sche wasserstoffhaltige amorphe Kohlenstoff-schicht	Metallhal-tige wasserstoffhaltige amorphe Kohlenstoff-schicht	Modifizierte wasserstoff-haltige amorphe Kohlenstoff-schicht	Nanokristal-line CVD-Diamant-schicht	Mikrokristal-line CVD-Diamant-schicht	Dotierte CVD-Diamant-schicht	CVD-Diamant	Dotierter CVD-Diamant	Graphit-schicht		
Empfohlene Abkürzung	-	a-C	ta-C	a-C:Me (Me = W, Ti ...)	a-C:H	ta-C:H	a-C:H:Me (Me = W, Ti ...)	a-C:H:X (X = Si, O, N, F, B ...)	-	-	-	-	-	-		
Weitere verbreitete, nicht mehr zu verwendende Bezeichnungen		DLC, graphit-artiger Kohlenstoff	DLC, i-C, Diamant, amorpher Diamant	Me-DLC, DLC	DLC, a-DLC, Hartkohlenstoff	DLC	DLC, Me-DLC, MeC:H, MeC:H, Metal-Carbon	DLC	PCD, PD, NCD	PCD, PD	PCD, PD	Diamantkeramik, TFD	Diamantkeramik			
Englischer Name	plasma-poly-mer film	hydrogenfree amorphous carbon film	tetrahedral hydrogenfree amorphous carbon film	metal-containing hydrogen-free amorphous carbon film	hydrogenated amorphous carbon film	tetrahedral hydrogenated amorphous carbon film	metal-containing hydrogenated amorphous carbon film	modified hydrogenated amorphous carbon film	nanocrystal-line CVD diamond film	microcrystal-line CVD diamond film	doped CVD diamond film	CVD diamond	doped CVD diamond	graphite film		
Abscheidungsverfahren	PA-CVD	PVD	PVD	PVD	PVD, PA-CVD	PVD, PA-CVD	PVD + PA-CVD, PA-CVD	PVD + PA-CVD, PA-CVD	aktivierte CVD	aktivierte CVD	aktivierte CVD	aktivierte CVD	aktivierte CVD	CVD, PVD		

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VDI 2840

- 9 -

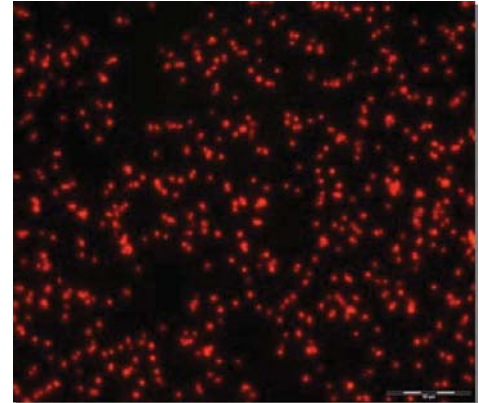
Table 1. Classification of carbon films; see also explanatory material in the text

Designation	Carbon films															
	1 Plasma polymer films	2 Amorphous carbon films (diamond-like carbon films/DLC)							3 Crystalline carbon films							
Thin film/thick film	Thin film	Thin film														
Doping, Additional elements		hydrogen-free			hydrogenated				undoped		doped		undoped		doped	
Crystal size on the growth side		(amorphous)														
Predominating C-C bond type	sp <sup>2</sup> or sp <sup>3</sup> , linear bond	sp <sup>2</sup>	sp <sup>3</sup>	sp <sup>2</sup>	sp <sup>2</sup> or sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>2</sup>	sp <sup>2</sup>	sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>3</sup>	sp <sup>2</sup>	
Film no.	1	2.1	2.2	2.3	2.4	2.5	2.6	2.7	3.1	3.2	3.3	3.4	3.5	3.6		
Designation	Plasma polymer film	Hydrogen-free amorphous carbon film	Tetrahedral hydrogen-free amorphous carbon film	Metal-containing hydrogen-free amorphous carbon film	Hydrogenated amorphous carbon film	Tetrahedral hydrogenated amorphous carbon film	Metal-containing hydrogenated amorphous carbon film	Modified hydrogenated amorphous carbon film	Nanocrystal-line CVD diamond film	Microcrystal-line CVD diamond film	Doped CVD diamond film	CVD diamond	Doped CVD diamond	Graphite film		
Recommended abbreviation	-	a-C	ta-C	a-C:Me (Me = W, Ti ...)	a-C:H	ta-C:H	a-C:H:Me (Me = W, Ti ...)	a-C:H:X (X = Si, O, N, F, B ...)	-	-	-	-	-	-		
Other designations commonly encountered but which should no longer be used		DLC, graphite-like carbon	DLC, i-C, diamond, amorphous diamond	Me-DLC, DLC	DLC, a-DLC, hard carbon	DLC	DLC, Me-DLC, MeC:H, MeC:H, metal-carbon	DLC	PCD, PD, NCD	PCD, PD	PCD, PD	Diamond ceramic, TFD	Diamond ceramic			
Deposition methods	PA-CVD	PVD	PVD	PVD	PVD, PA-CVD	PVD, PA-CVD	PVD + PA-CVD, PA-CVD	PVD + PA-CVD, PA-CVD	Activated CVD	Activated CVD	Activated CVD	Activated CVD	Activated CVD	CVD, PVD		

Bestimmung der Thrombozytenadäsion

Messung nach Methode von Breddin und Brück

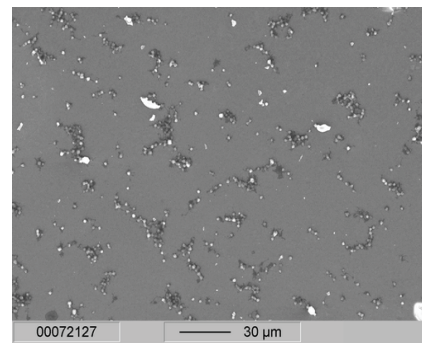
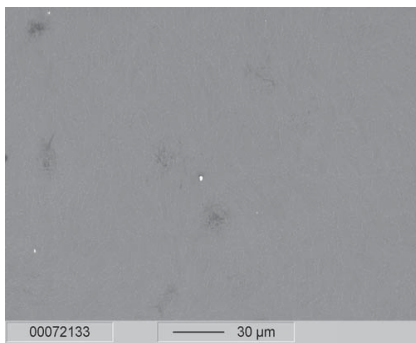
- Bereitstellung von frischem Citratblut (Eigenblut)
- zentrifugieren, bis sich PRP (platelet rich plasma) absetzt
- auf in Citratpuffer vorinkubierte Proben aufbringen
- 1h im Brutschrank bei 37° C auslagern
- Proben waschen
- Thrombozyten mit Fluoreszenzfarbstoff (Rhodamin 6G) einfärben
- Auszählung der Thrombozyten im Mikroskop



MEDICOAT – thrombocytes adhesion on a-C:X coatings

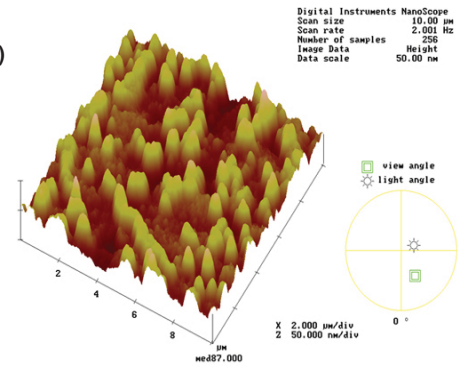
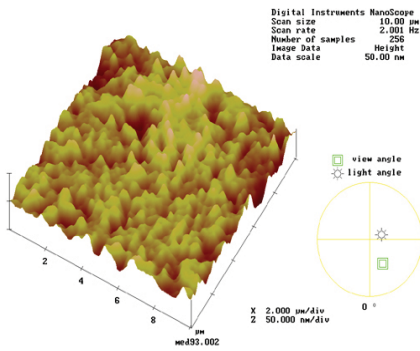
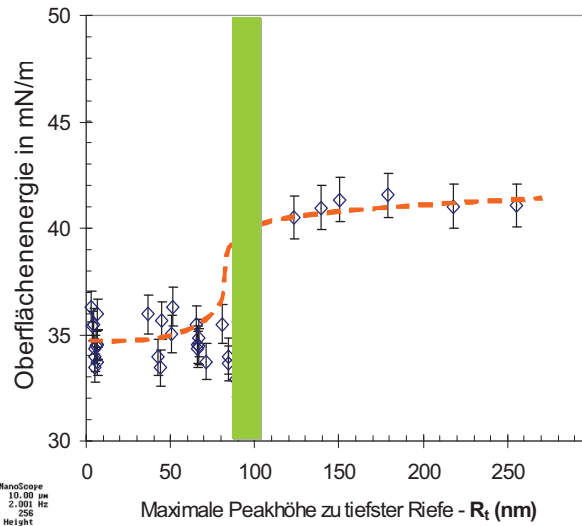
a-C coating with low thrombogenicity

a-C coating with high thrombogenicity



1550 – 1560 cm <sup>-1</sup>	Raman spectroscopy: G-band position	1565 – 1580 cm <sup>-1</sup>
34 – 40 mN/m	surface energy	30 – 34 mN/m
5 – 9 mN/m	polar fraction of SE	9 – 15 mN/m
65° - 77°	wetting angle of H <sub>2</sub> O <sub>dest</sub>	78° - 90°

**thrombocyte adhesion = f (surface energy, a-C constitution, morphology)**



**significance of  $R_t$   
for surface energy**